



SEMI® INTERNATIONAL STANDARDS

# Fiducial Mark Interoperability TF Report

As of September 11, 2015

# TF Leadership (No Change)

- **H. Tsunobuchi / KEYENCE**  
Traceability Committee
- **T. Nakai / SUMCO**  
Silicon Wafer Committee
- **S. Mashiro / Tokyo Electron**  
Physical Interface and Carrier Committee
- **S. Masuchi / DISCO**  
Assembly and Package Committee
- **M. Matsuda / Hitachi Kokusai**  
Information and Control Committee

# Recent TF activity

- TF meeting on April 27, 2015 and June 11, 2015
- T7 issues
  - Traceability Japan TC Chapter assigned following up activity for T7 to Fiducial Mark Interoperability TF
    - Section 2.1 (T7 adoption of non-silicon materials)
    - Figure 3 small modification
    - M20 coordinate system (based on negative to 5752 [withdrawn])
  - TF decided to delete all position specifications from SEMI T7 because position specifications are also described on SEMI M1 and other related Silicon Standard.
  - SNARF was approved by GCS. (SNARF 5890)
  - Document 5890 is submitting to Cycle 7.
  - To be adjudicated at the next JA TC Chapter meeting of Traceability TC in conjunction with SEMICON JAPAN 2015.
- Others
  - Silicon: Give up to develop new Standard for 450mm Development Wafer with fiducial Mark
  - Assembly and Packaging: Discussing backend alignment issues with introducing fiducial mark wafer.

# Next Meeting

- TBD (around the end of October)
  - T7 Revision
    - Ballot result discussion of Document 5890